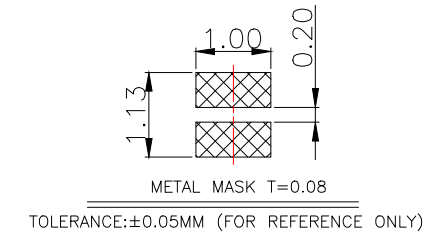
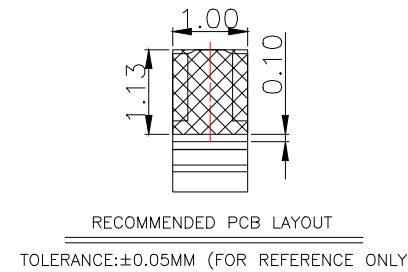
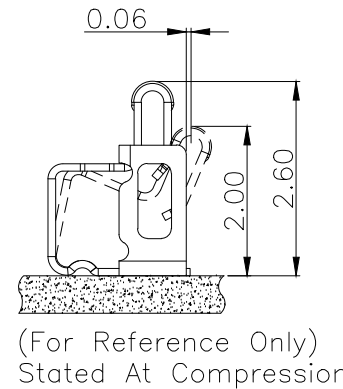
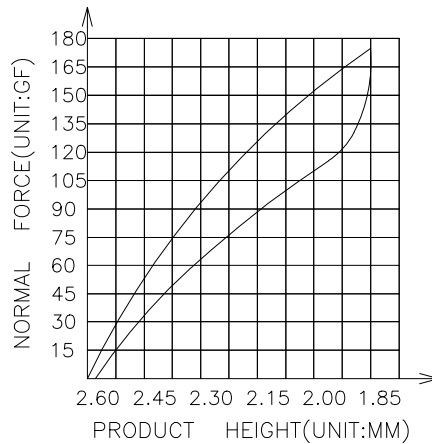
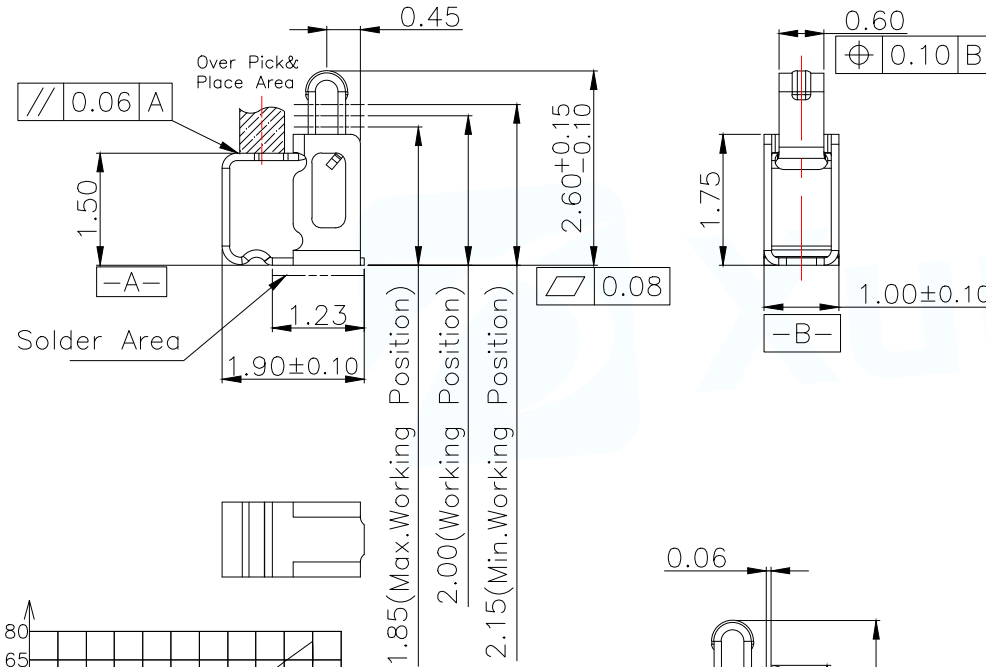
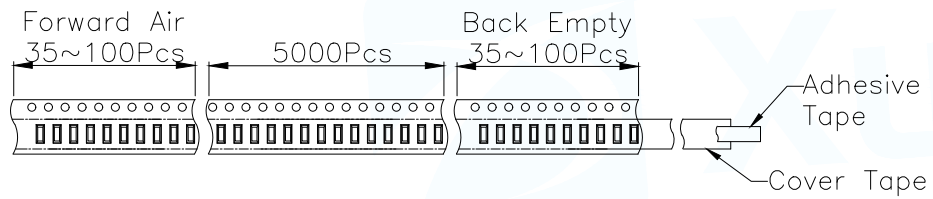
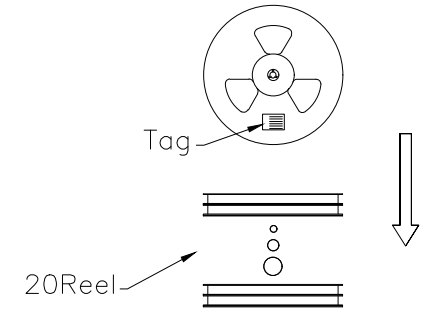
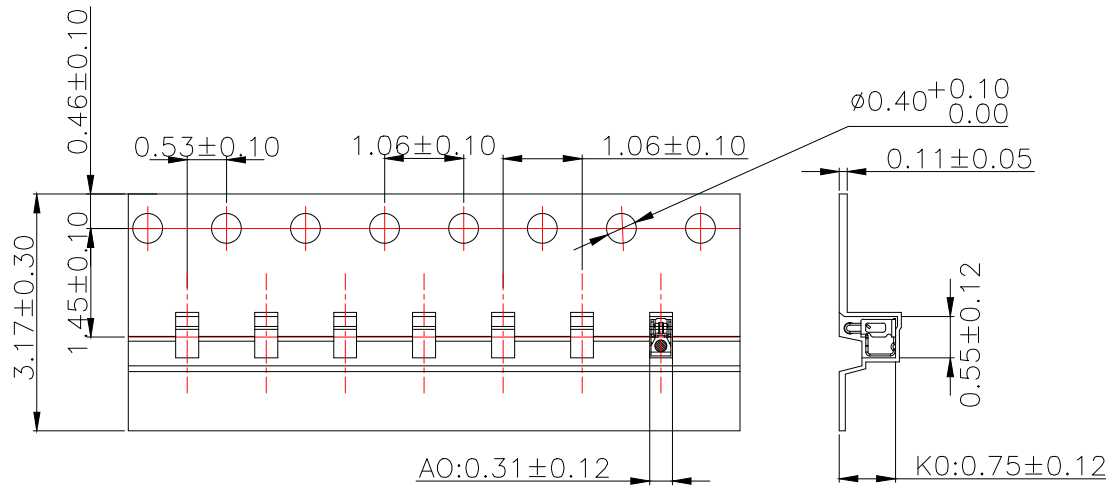


NOTES:

- 1:MATERIAL
  - 1-1: SUS-301 THICKNE=0.10MM
- 2:SPECIFICATIONS
  - 2-1: RATED CURRENT: 1.0A
  - 2-2: VOLTAGE RATING: 1.5V
  - 2-3: CONTACT RESISTANCE: 80mΩ/MAX
  - 2-4: WELDING THRUST:≥3KG
  - 2-5: OPERATING TEMPERATURE: -40°C~+85°C
- 3:DURABILITY: 1500 CYCLES
- 4:SALT SPRAY TIME: 24H
- 5:ELECTROPLATE: THE NICKEL-PLATED SUBSTRATE IS 50u" MIN
- 6:REQUIREMENTS
  - 6-1:TERMINAL TO EAT FULL TIN,NOTPEELING, WELDING OBVIOUS COLOR AND OTHER ADVERSE
  - 6-2:ROHS.REACH.HF HALOGER ADVERSE OF DOMESTIC AND INTERNATIONAL ENVIRONMNTAL REQUIREMENTS

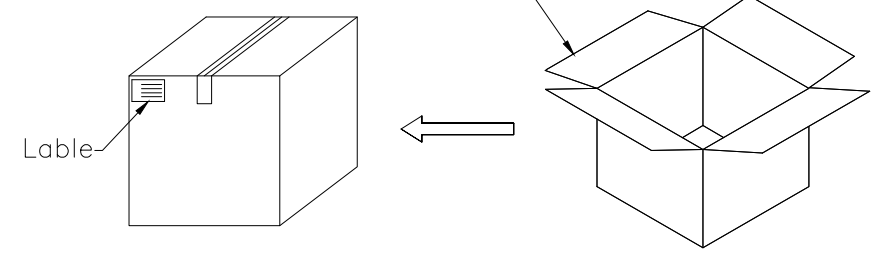


MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 天线弹片 L1.90*W1.00*H2.60
			PAR ASP-D2601-B31
DECIMALS:	ANGLES:		DWN Lucas
X.:±0.30	X':±2°		CHKD Ethan
X.X:±0.20	X.X':±1°	APVD Jacob	SCALE1:1 UNIT:MM
X.XX:±0.15	X.XX':±0.5°	CUSTOMER COPY	SIZE:A4 SHEET:1F1 REV:A

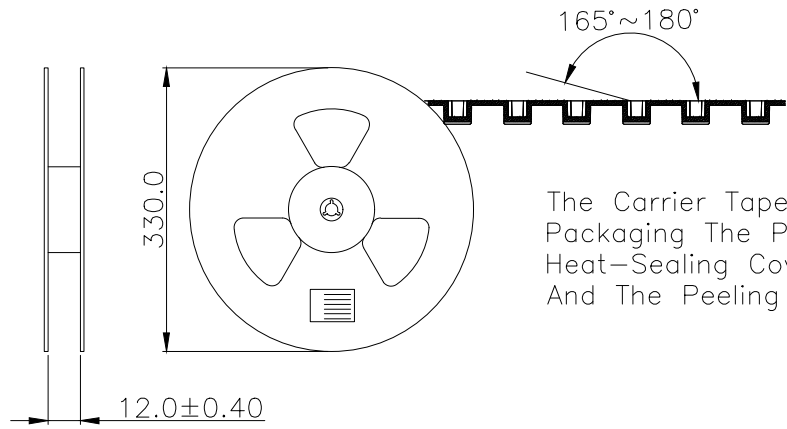


Carton Size  
290\*330\*4 K3K

Carton Size  
345\*345\*360 K=K



Customer To Use Direction  
Pull Out Direction (出料方向)



The Carrier Tape Is Heat-Sealed Packaging The Peeling Angle Of The Heat-Sealing Cover Tape Is 165°~180° And The Peeling Force Is 30~120g.

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 天线弹片 L1.90*W1.00*H2.60
			PAR ASP-D2601-B31
DECIMALS:	ANGLES:		DWN Lucas
X.:±0.30	X.':±2°		CHKD Ethan
X.X:±0.20	X.X':±1°	APVD Jacob	SCALE 1:1 UNIT:MM
X.XX:±0.15	X.XX':±0.5°	CUSTOMER COPY	SIZE:A4 SHEET:1F1 REV:A

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